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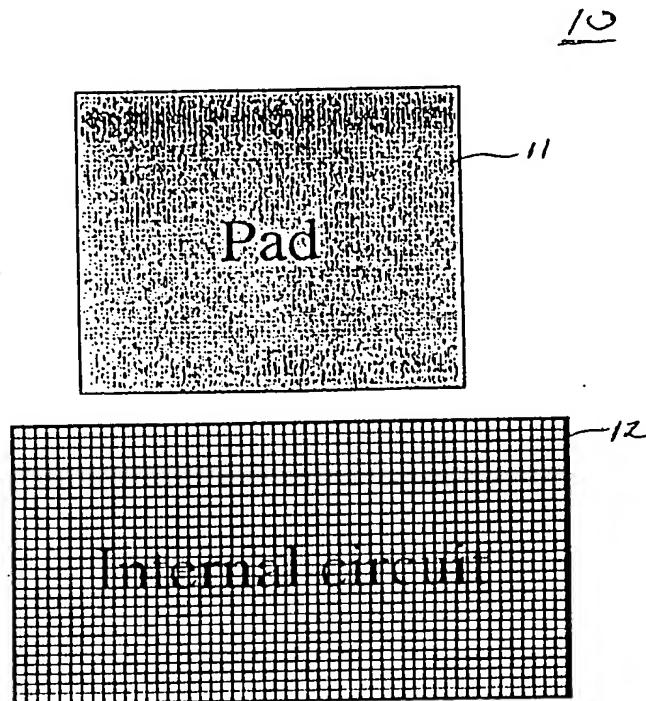
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Top side view

(CONVENTIONAL ART)

Fig. 1

AMIS - AF01210

FIG. 2

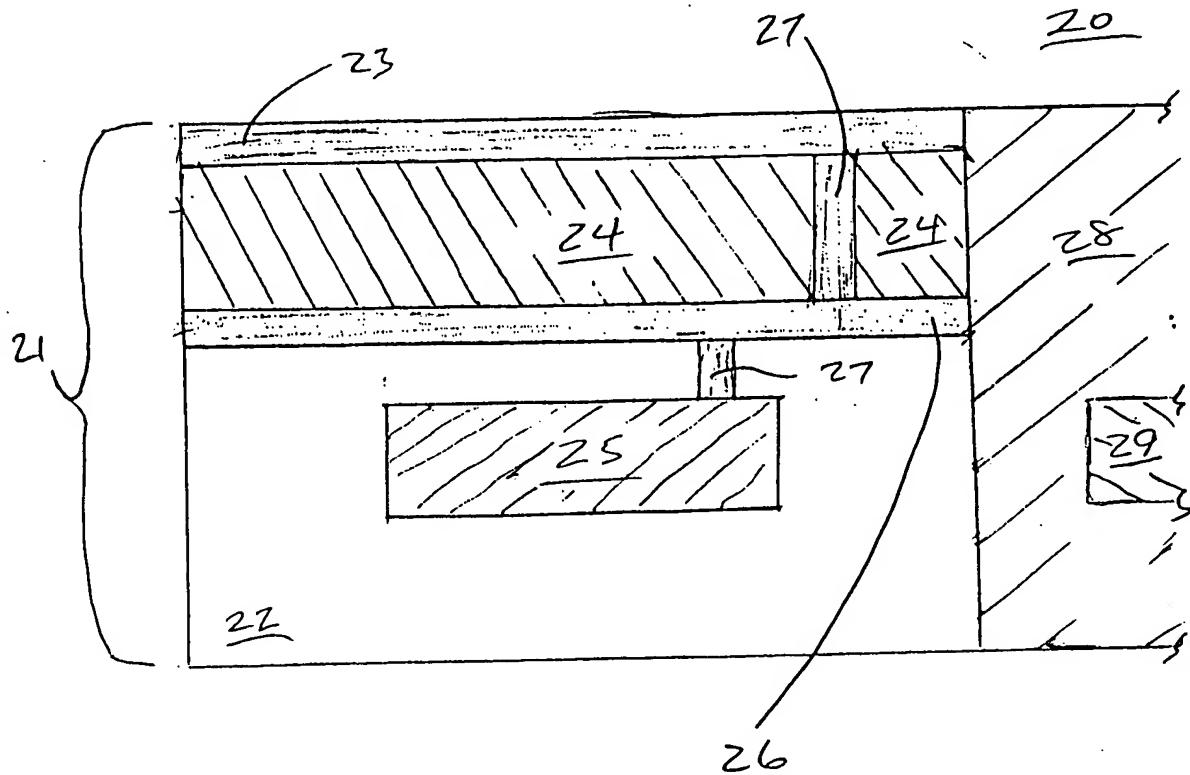
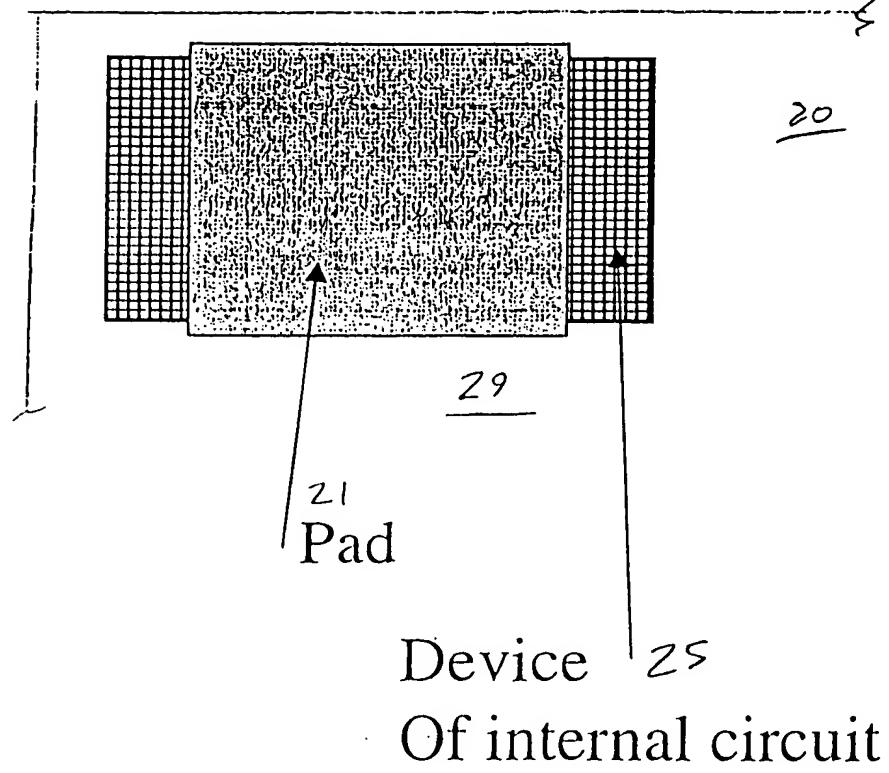


Fig. 2

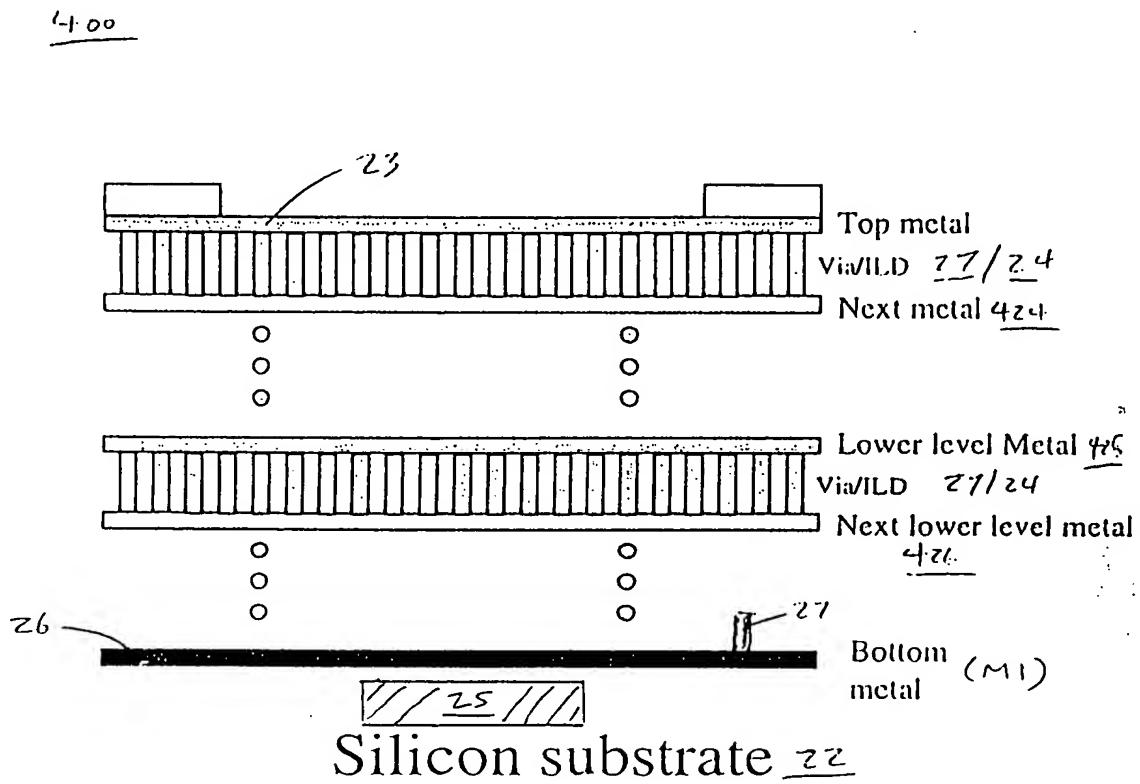


Top side view

Fig. 3

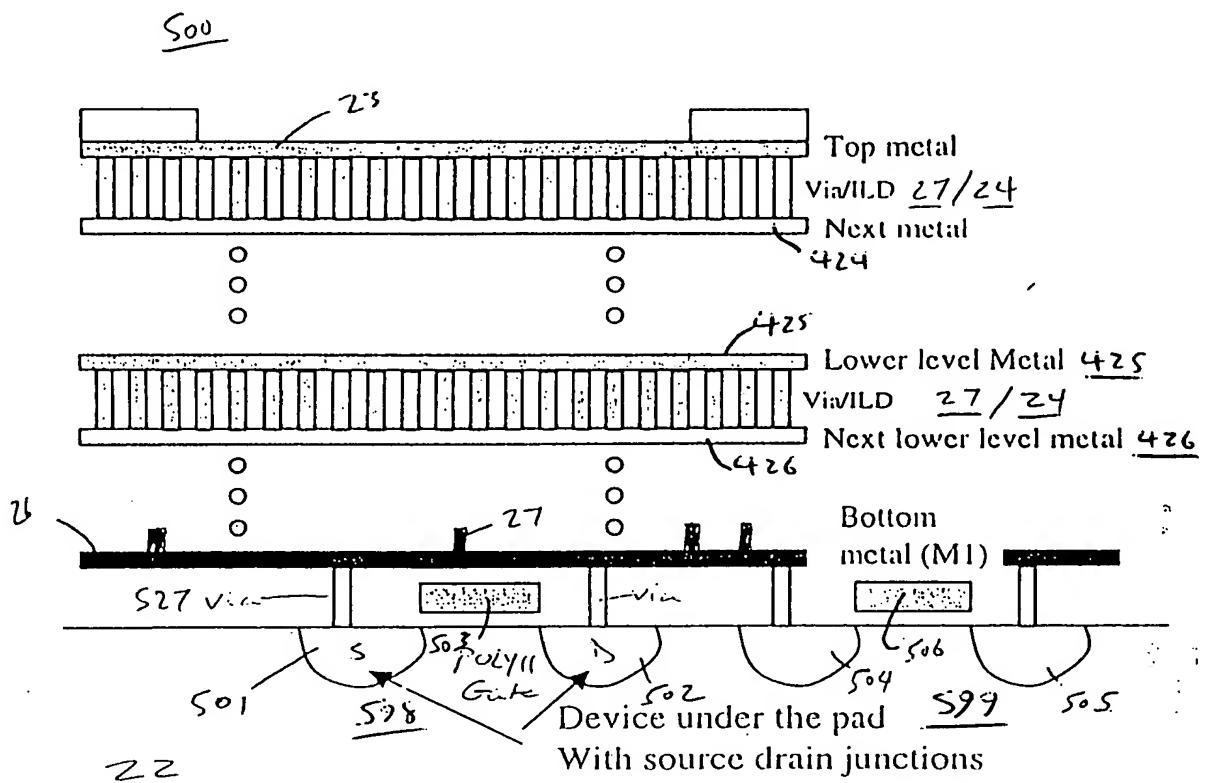
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Fig. 4



Cross section view

Fig. 4



Cross section view

Fig. 5

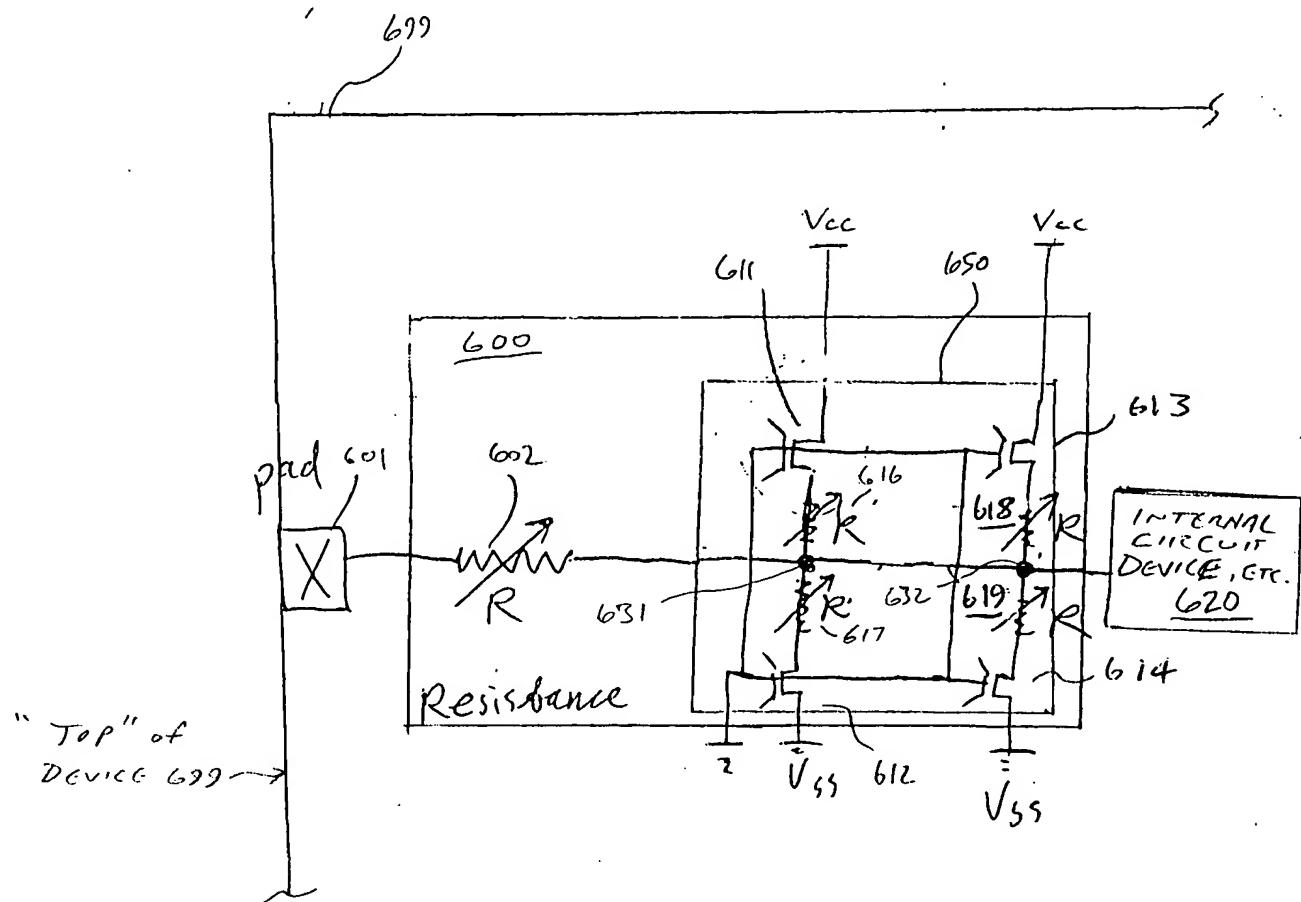
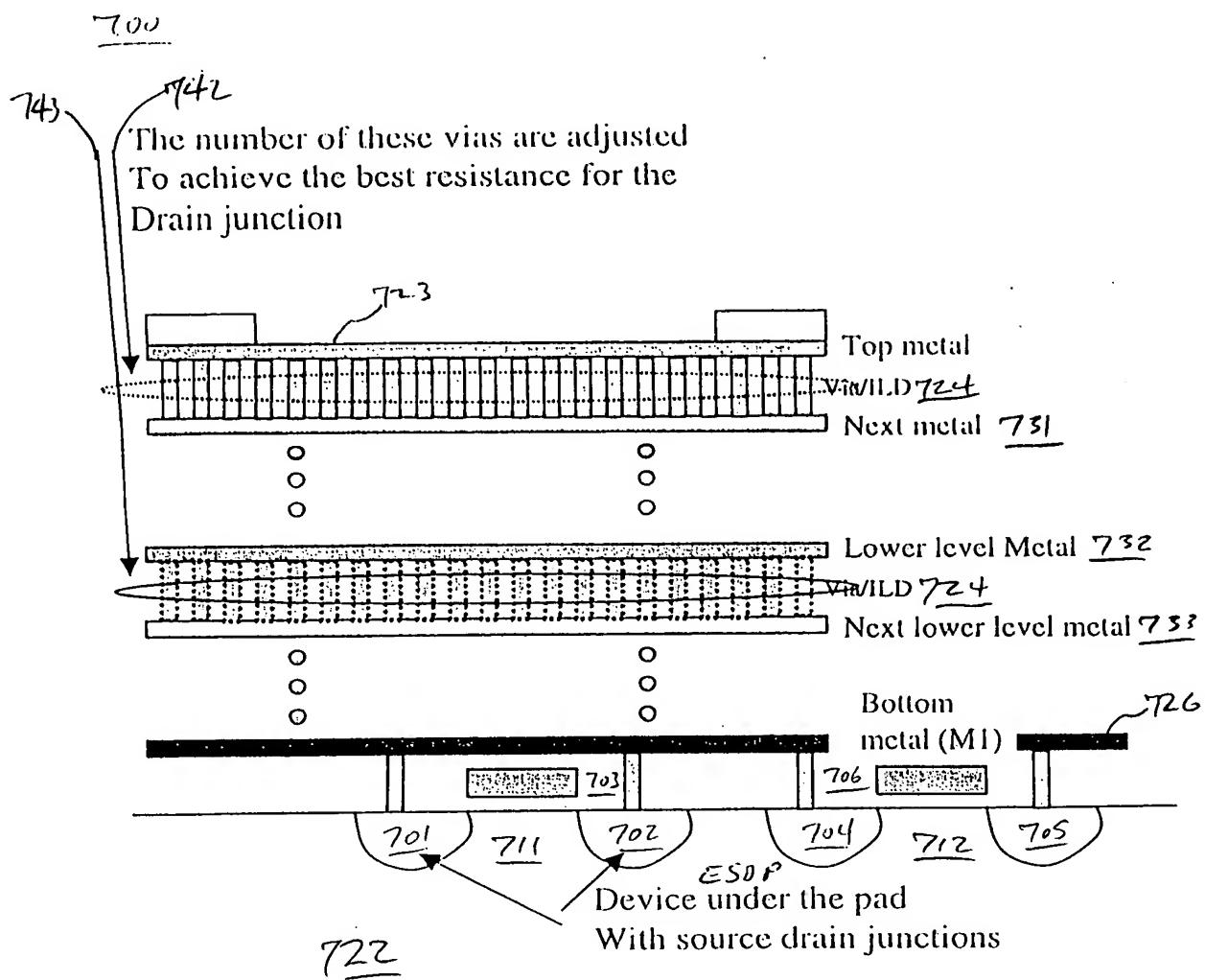


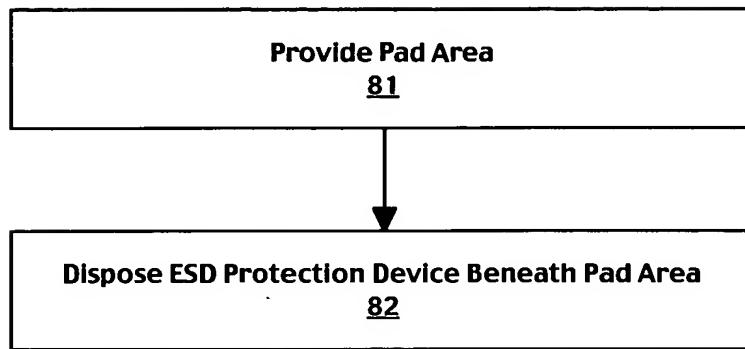
Fig. 6



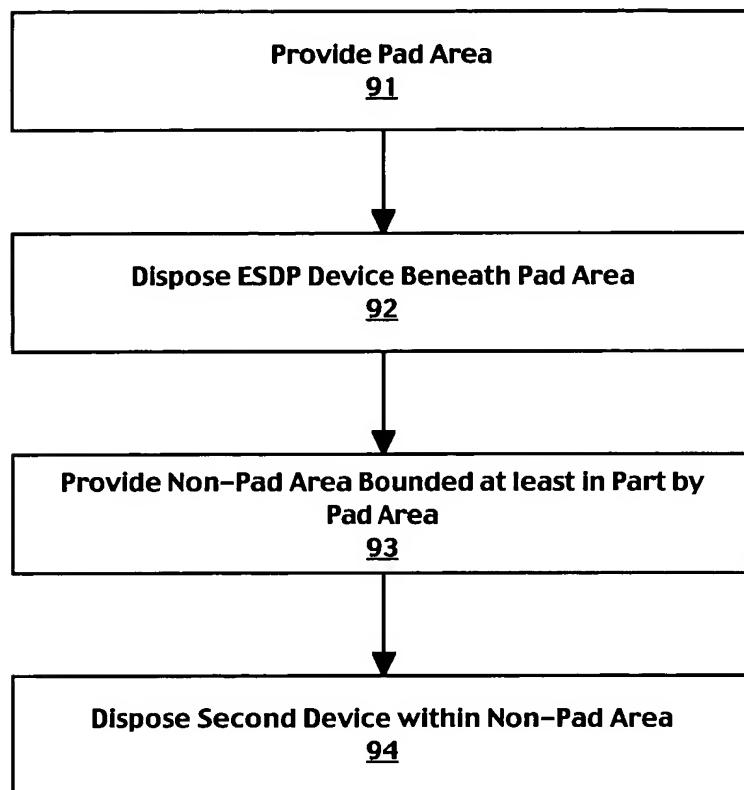
Cross section view

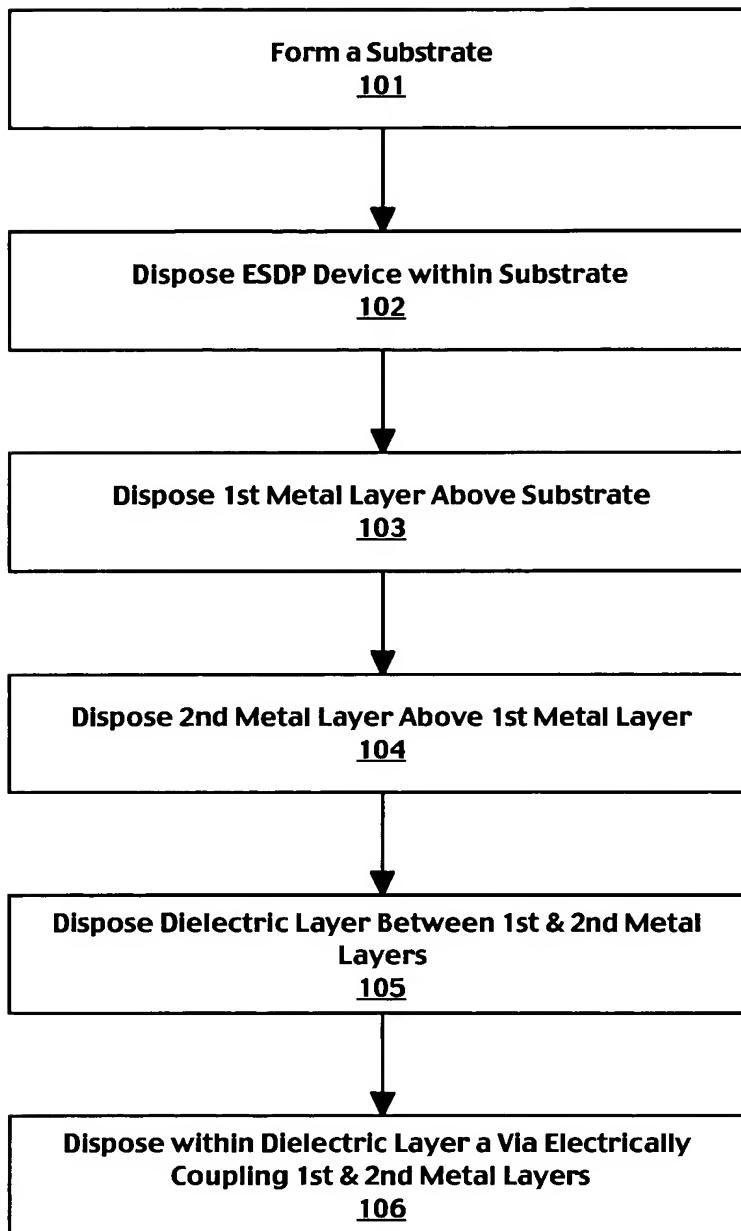
Fig 7

**80    Fabricating a Semiconductor Structure with ESD Protection**

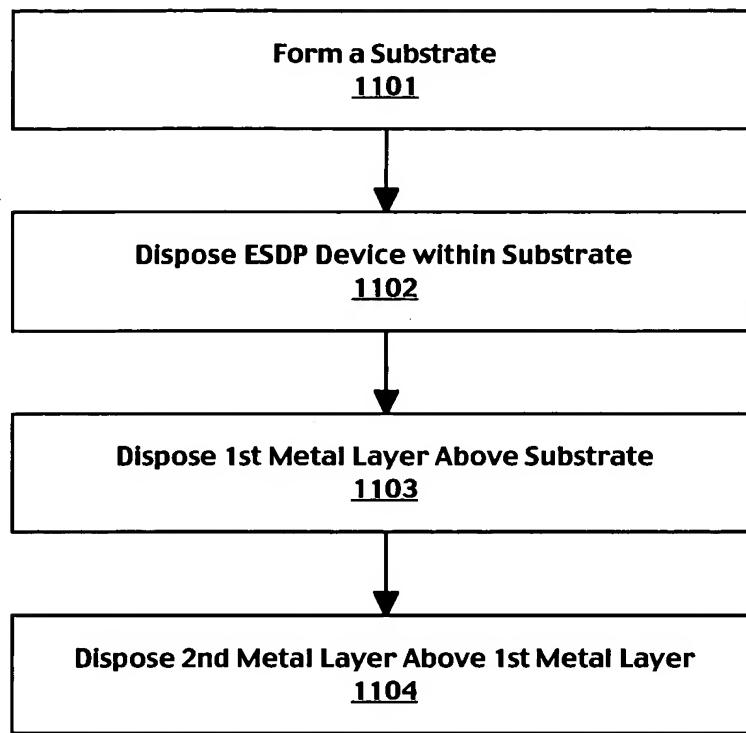


**Fig. 8**

90**Fabricating a Semiconductor Structure****Fig. 9**

100**Fabricating a Pad Area****Fig. 10**

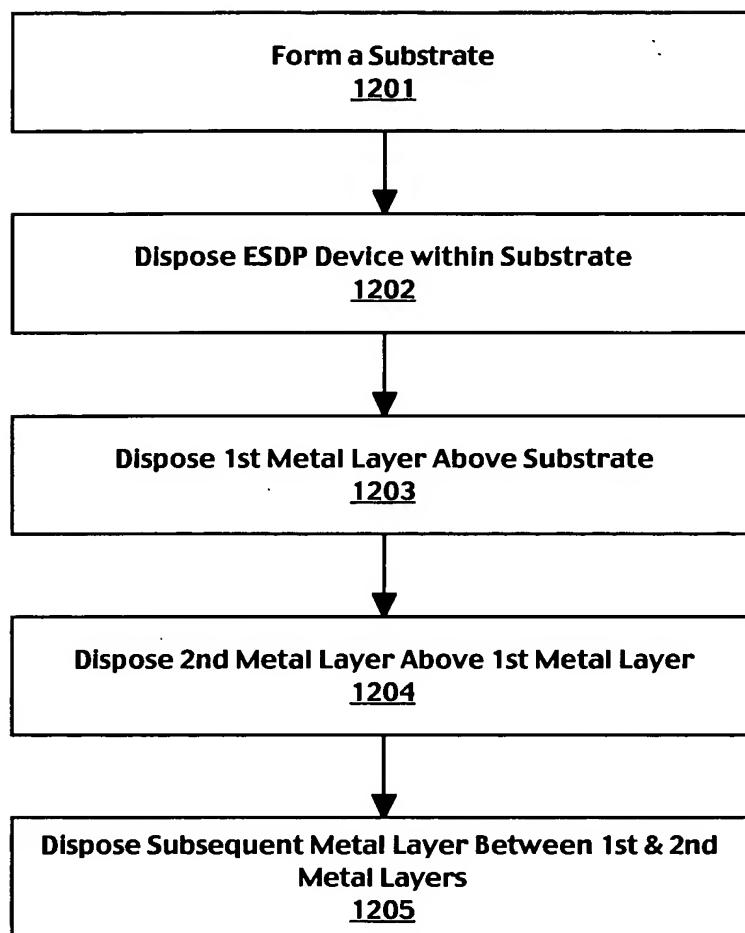
**1100    Fabricating a Pad Area with ESD Protective Device Below**



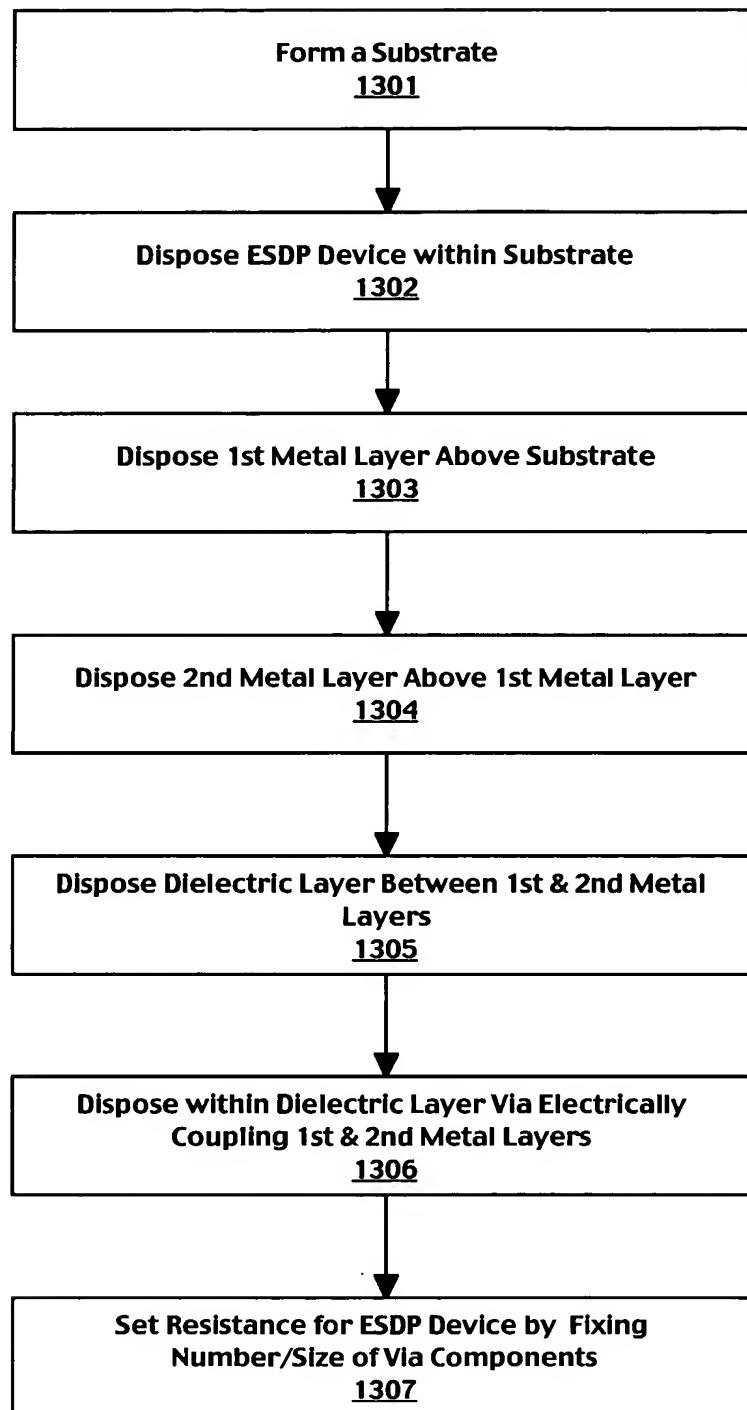
**Fig. 11**

1200

**Fabricating a Pad Area with ESDP Below**



**Fig. 12**

1300**Fabricating an ESDP Device****Fig. 13**